

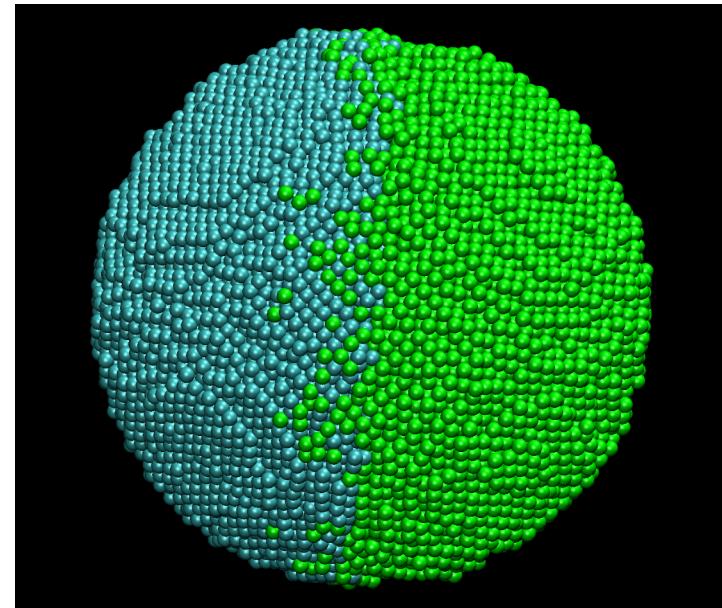
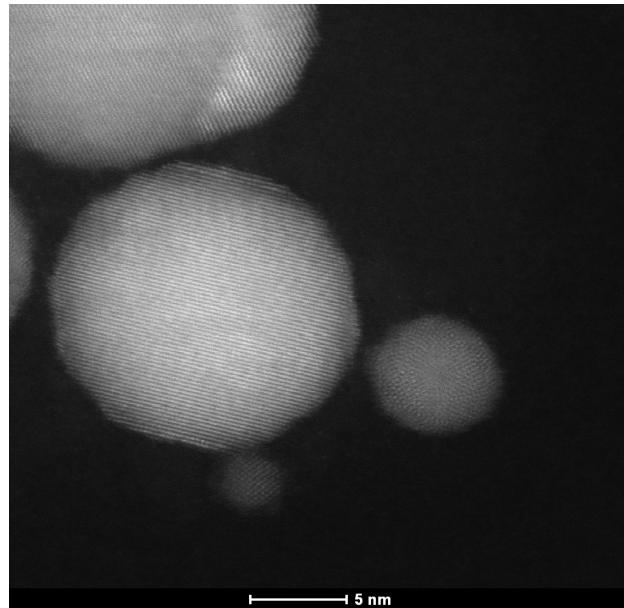


Bonding of Metallic Nanoparticles

SAND2013-3557C

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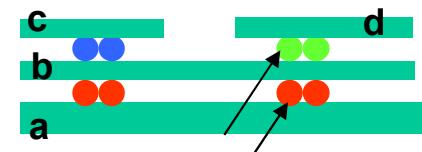
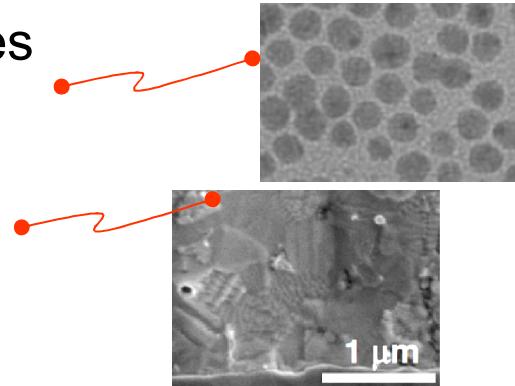


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Nanoparticle Solders

- Metallic NP nanosolders offer two advantages
 - Low processing temperatures
 - High service temperatures
- Example: Ag/Cu
 - Bonding at $\sim 200^{\circ}\text{C}$
 - Applications above 350°C
- Enable step-soldering for stacked (3D) package
 - Increases functionality, reliability
 - Does not increase footprint
- Critical parameters controlling the metal/metal interfacial reactions are not understood

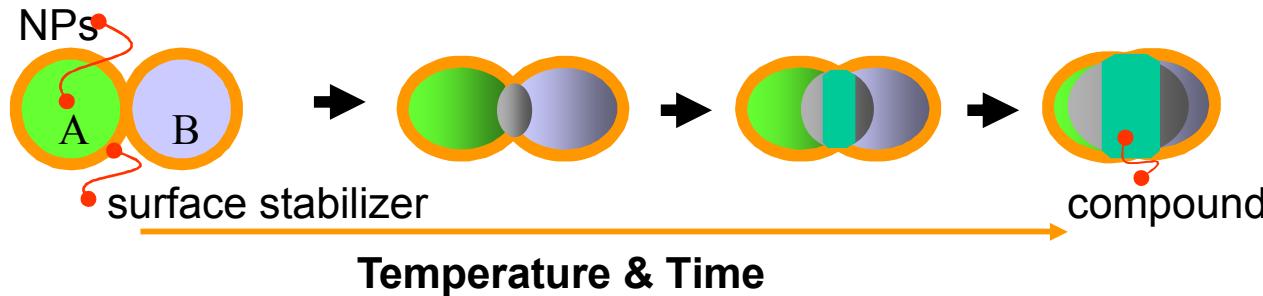


Different color shows
different soldering steps

R&D Goals & Approach

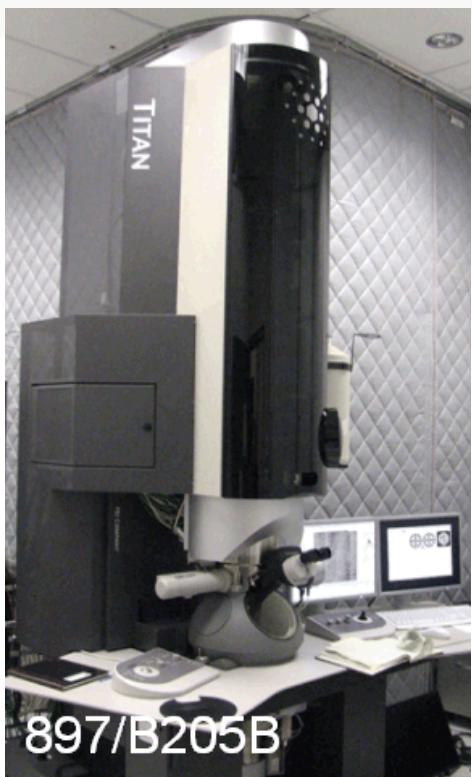
Goals: *Identify, understand and control* the key properties that affect bonding formations at NP metal interfaces

- In-situ, dynamic TEM observation & Atomic-scale MD modeling

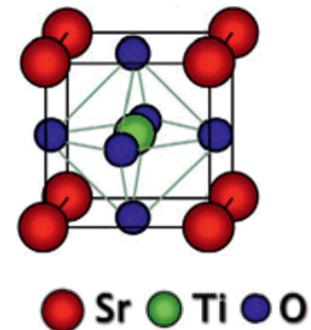
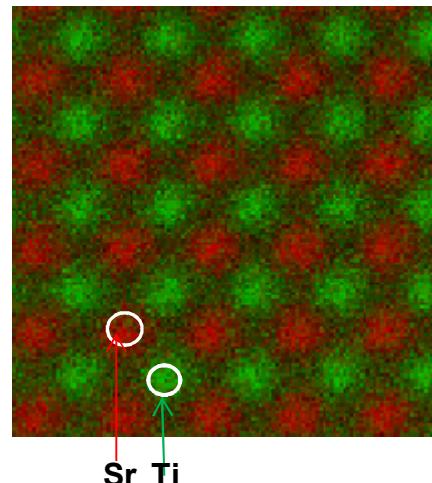
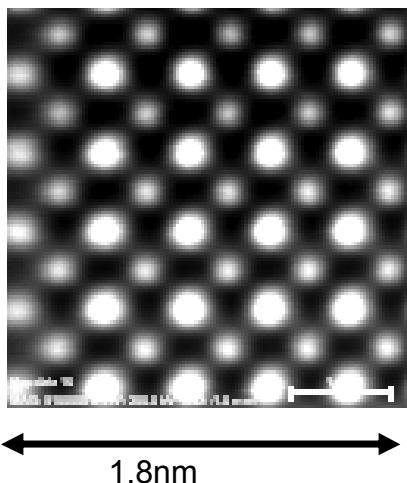


- *In-situ, aberration-corrected STEM will be used to obtain atomic-scale, compositional maps (at T, t).*
- *Direct comparison* between the experiment and theory (MD) will be used to understand the reaction model.

Aberration Corrected STEM

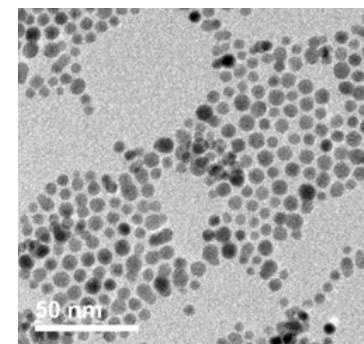
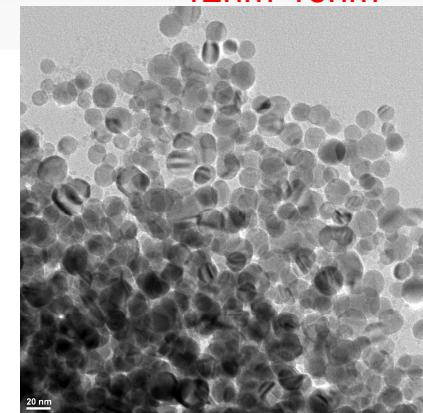
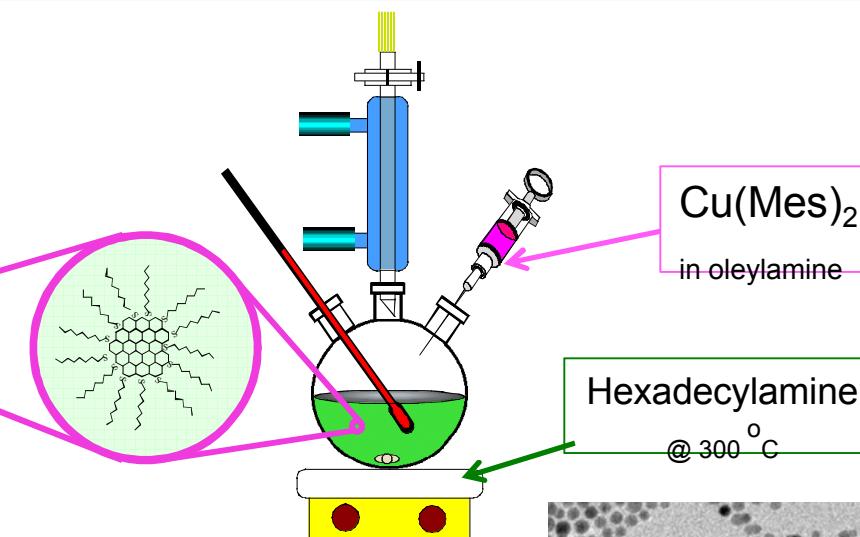
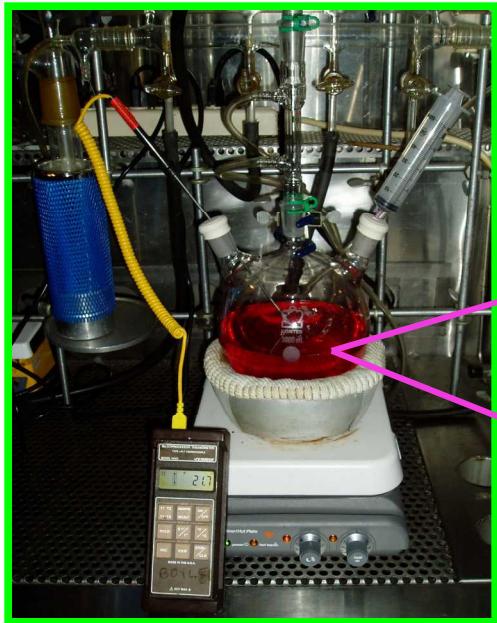


HAADF Z-contrast imaging Atomic-scale element map

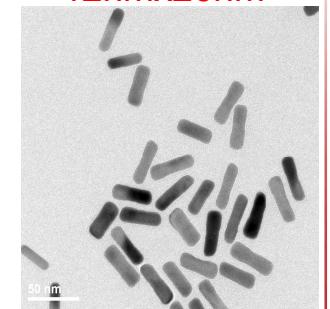


- FEI Titan G2 with *ChemiSTEM Technology*
 - Advanced spherical aberration correction
 - Super-bright field emission electron gun
 - Four Si drift detectors
 - 1000°C/sec thermal ramp
- Unprecedented capabilities
 - Sub-atomic scale STEM (80-120 pm)
 - Atomic scale chemical mapping
 - Light element detection
 - Low energy operation for sensitive materials

Nanoparticle Creation

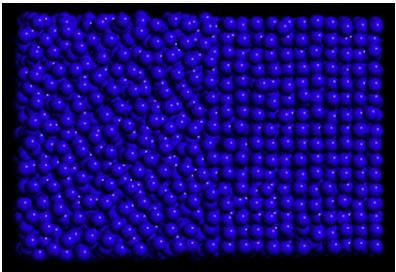


Au NP rods
~12nmx26nm

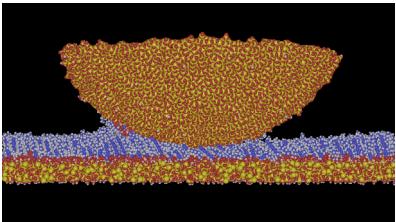


- Solution Precipitation – inject something cold into something hot
- Variety of particles
- Different shapes, sizes
 - Spheres
 - Rods

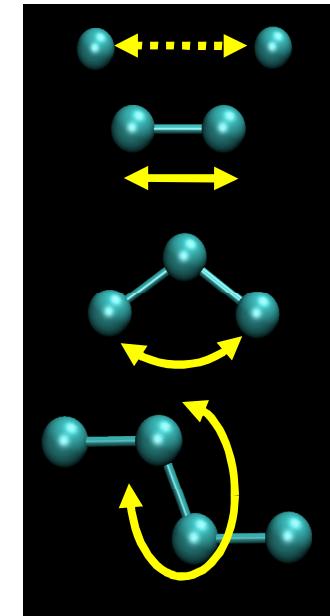
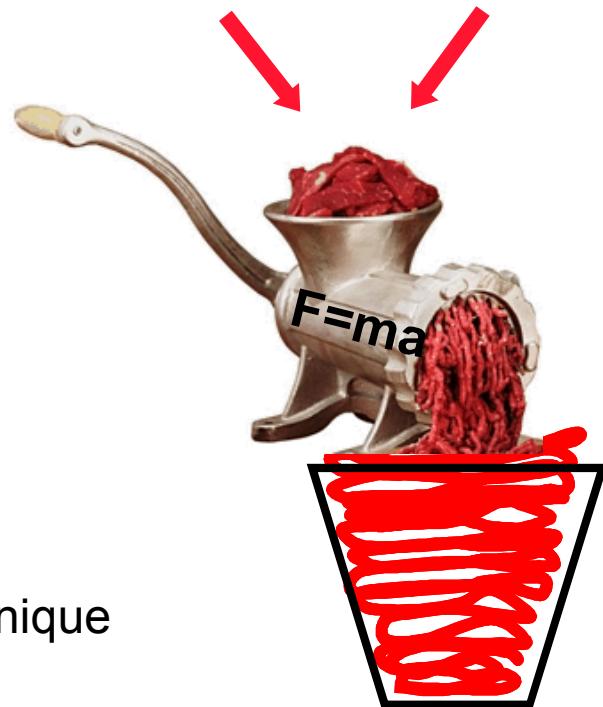
Molecular Dynamics Modeling



Initial positions
and velocities



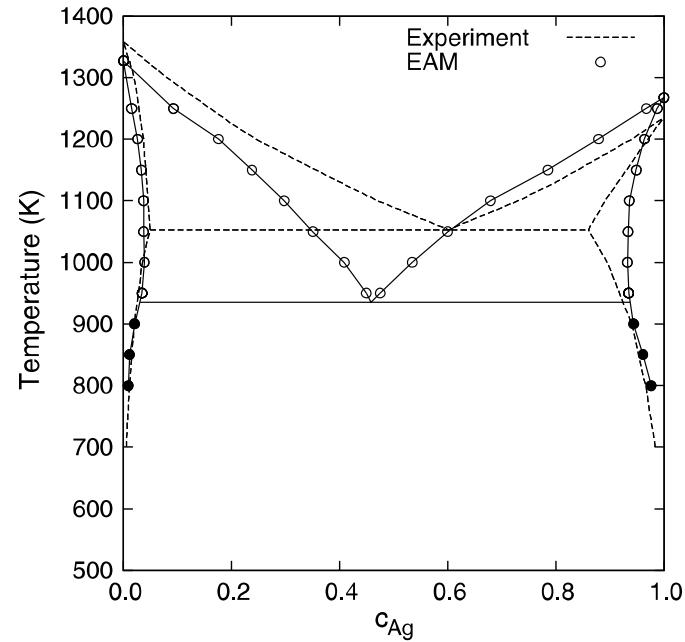
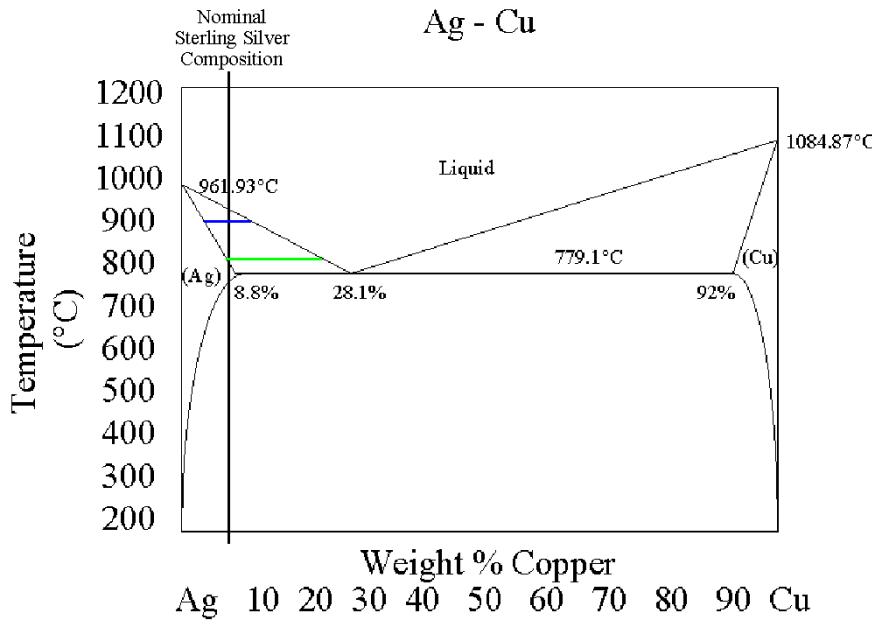
Interatomic
potential



Positions and
velocities at
later times

- Classical simulation technique
- Empirical interactions
- Evolve system, analyze
- Also performed Monte Carlo substitutions

Ag/Cu Phase Diagram



- Eutectic system
- Not miscible
- This is bulk, is nanoscale different?
- Model phase diagram matches very well

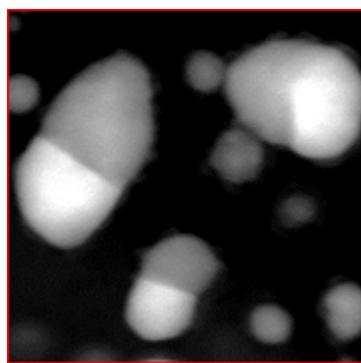
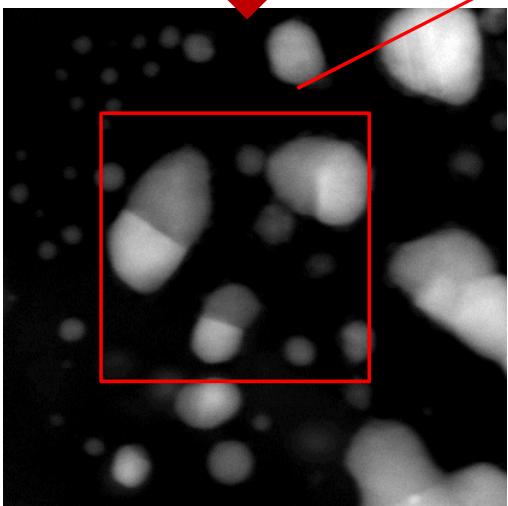
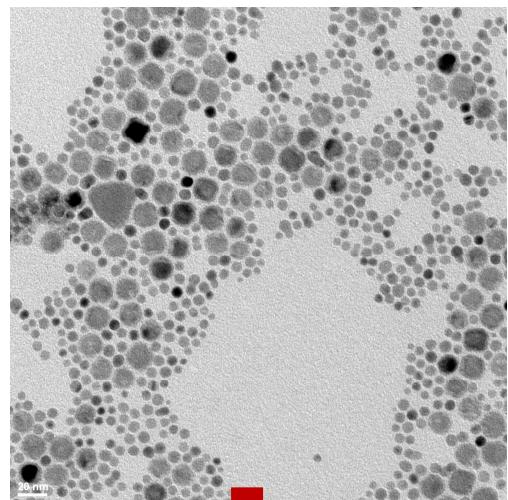
Initial Experiments

Cu/Ag dispersed on C film

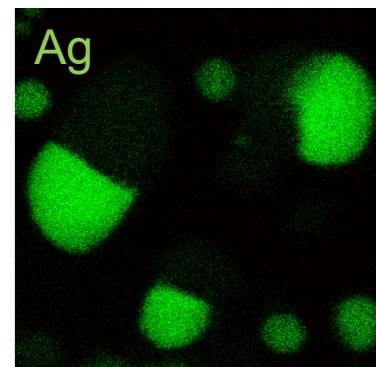
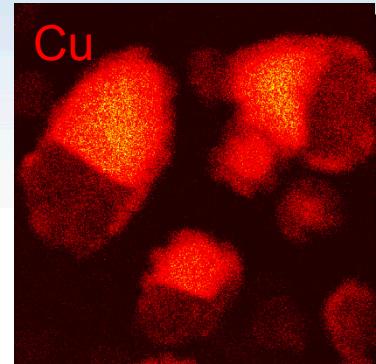
Ag – 5-6 nm

Cu – 12-15nm

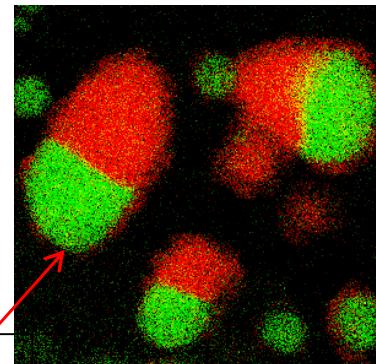
300°C
1 minute



105nm

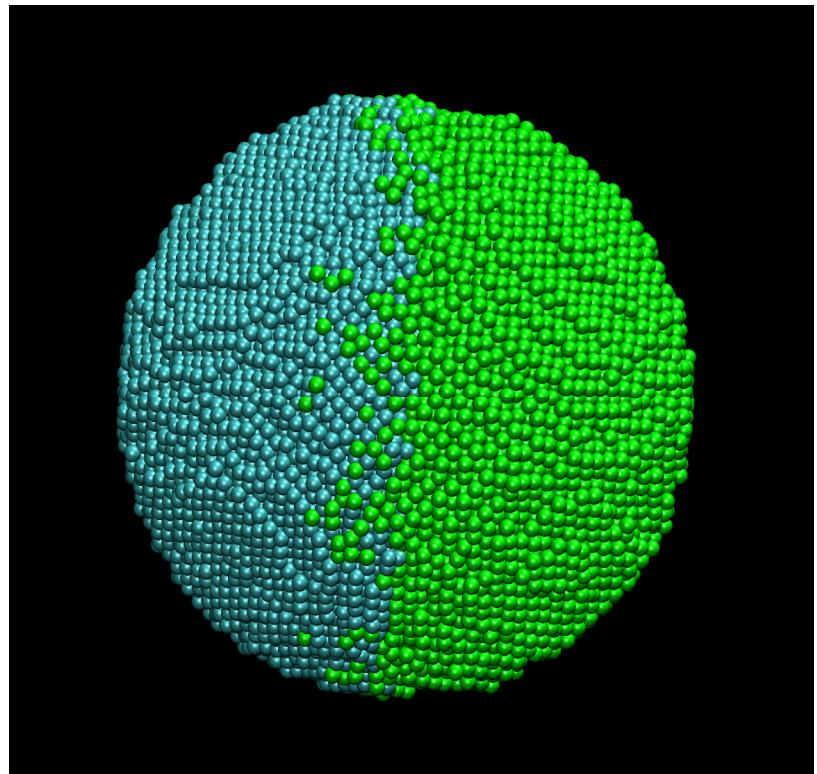
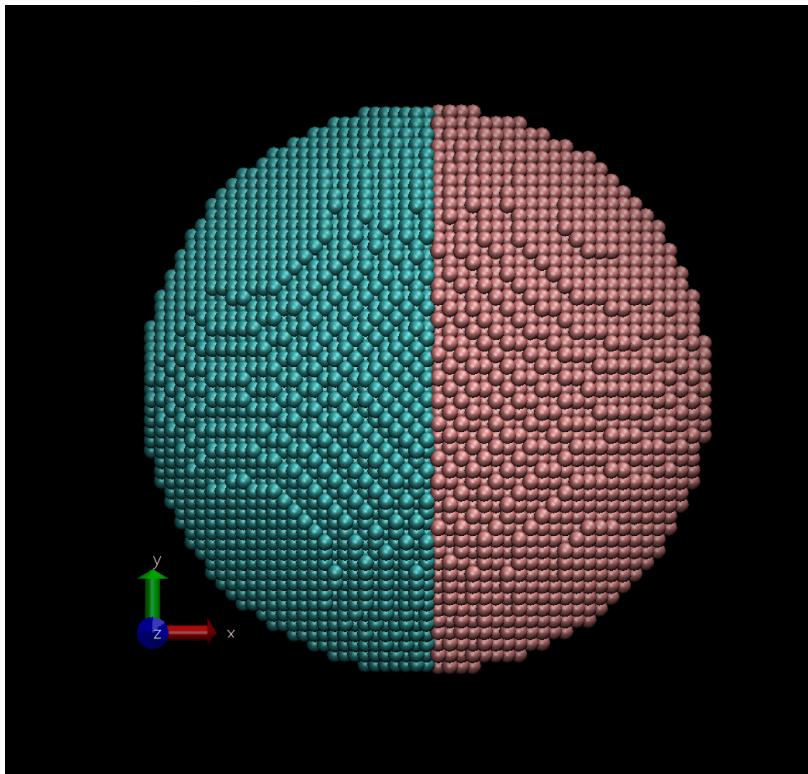


Thin layer of Cu
around Ag !





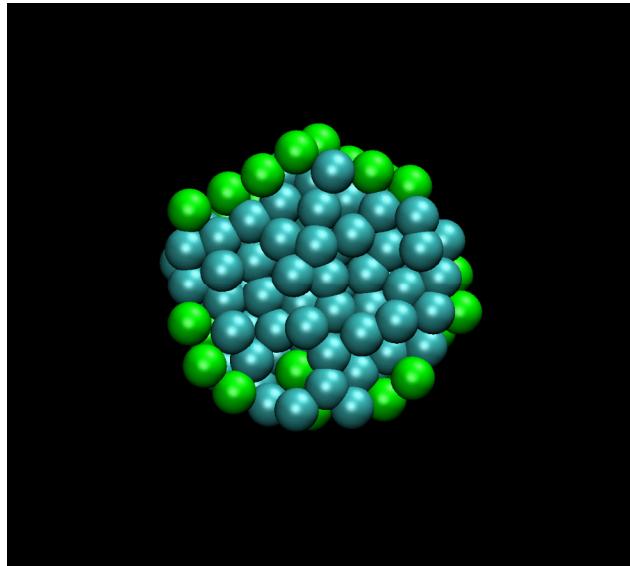
Simulation Results



- 10nm Janus nanoparticles (left half Cu, right half Ag)
- At 800K (below eutectic) for < 1 ns
- Shows opposite behavior



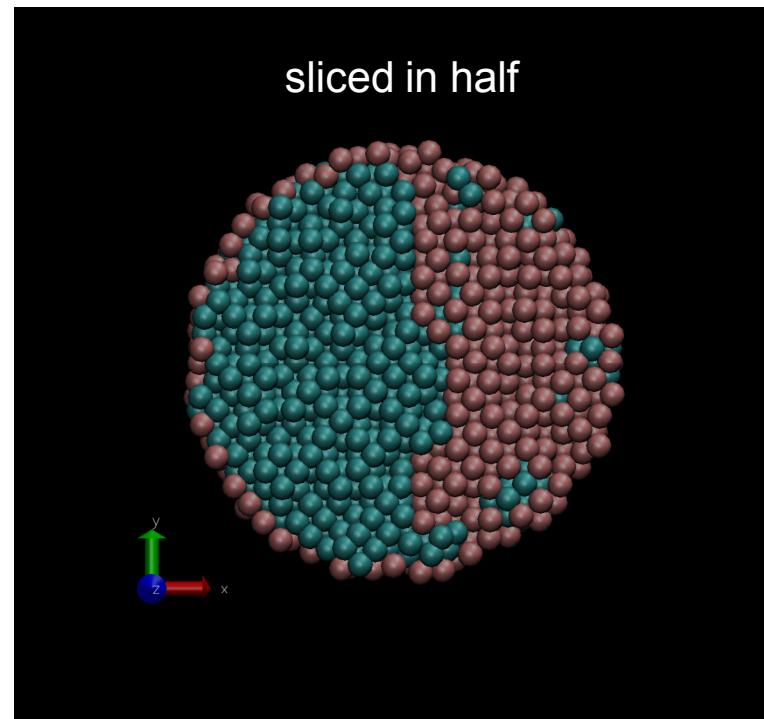
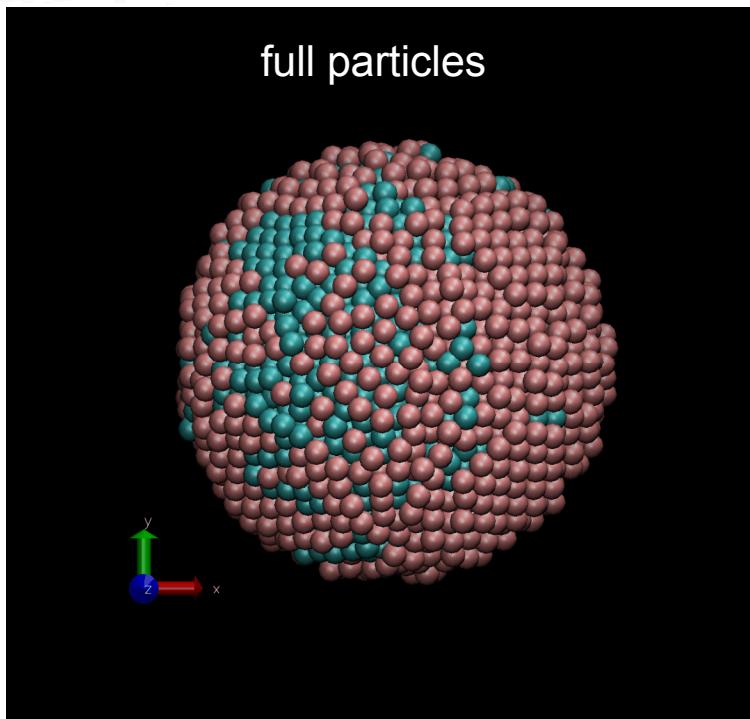
Smaller Particles



- 800K for 12.5 ns
- Particle cut in half for detail
- Complete silver shell formed



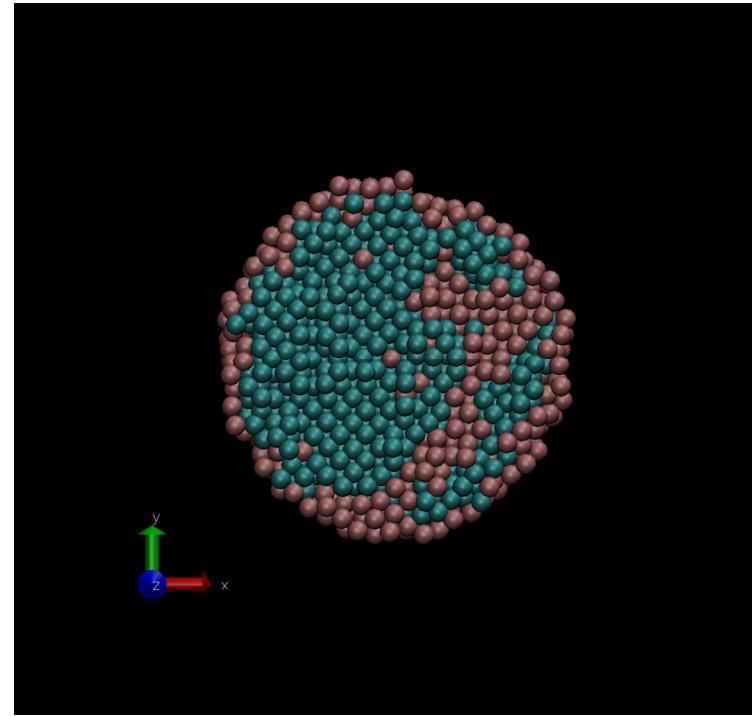
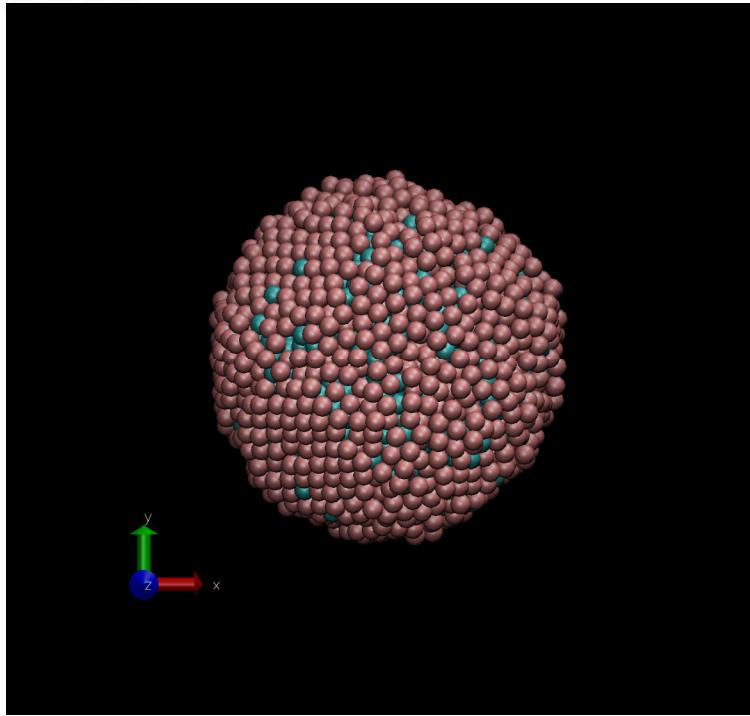
Monte Carlo Simulations



- Simulation is not real time, but can be slow
- Randomly pick two particles to swap (with small translation)
- Accept move if energy is lower, or according to Boltzmann
- 5nm particle after 20M steps



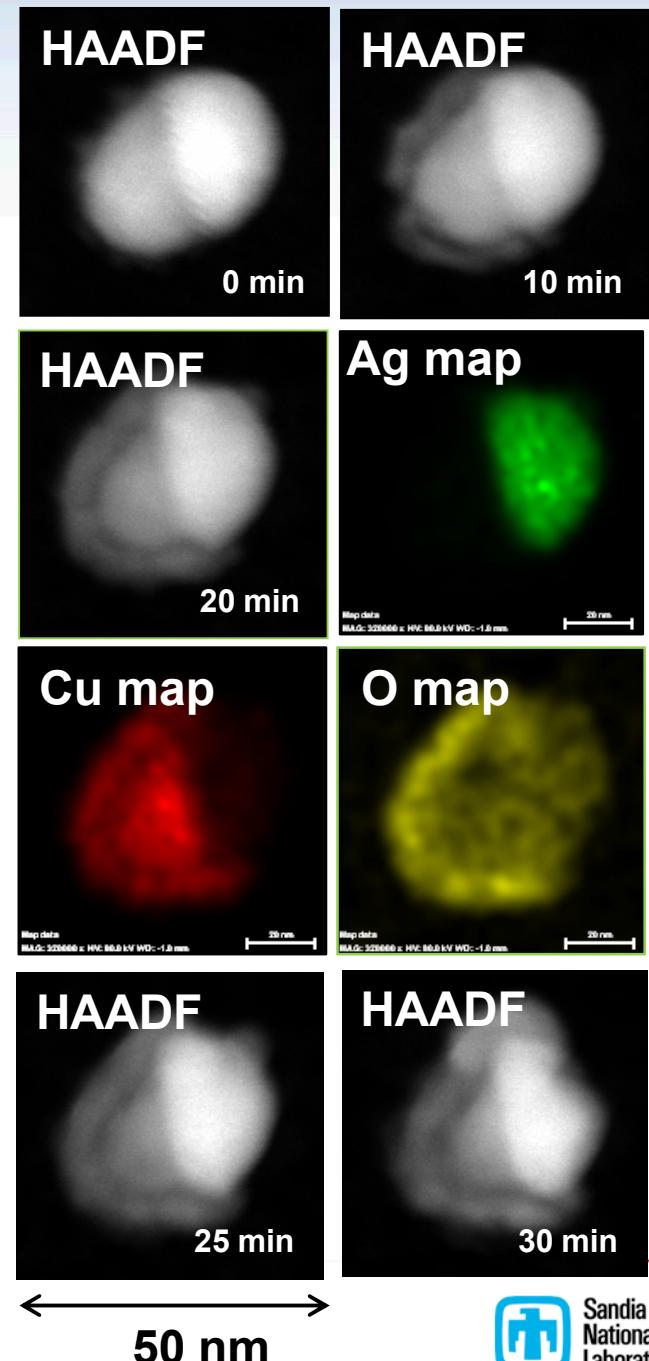
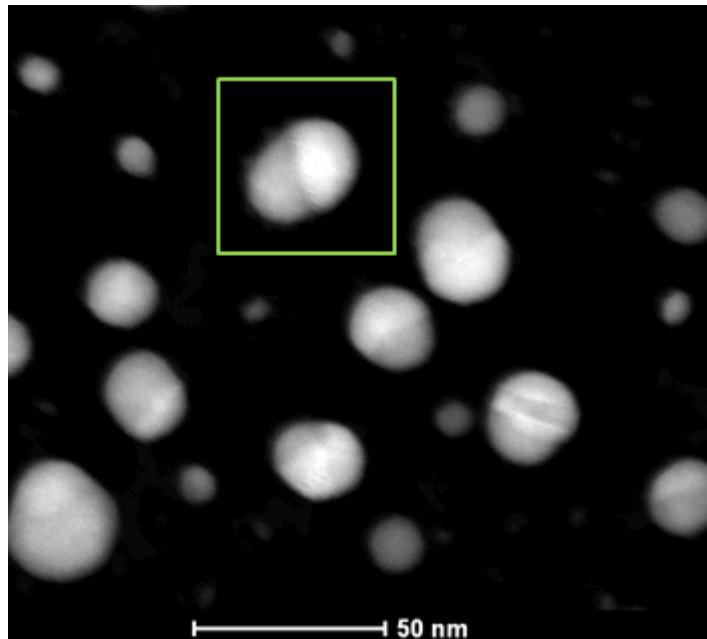
Longer Time Results



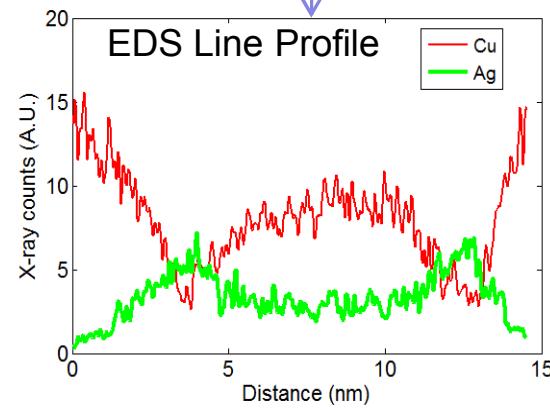
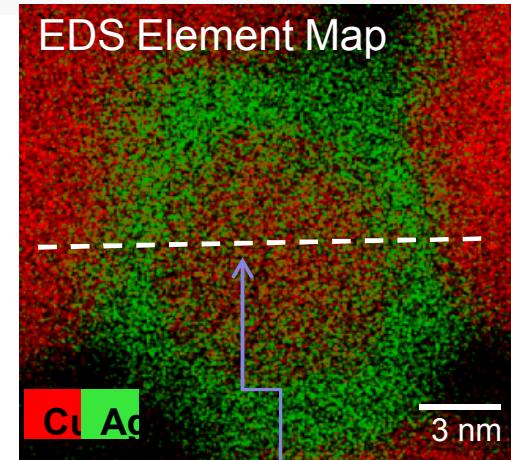
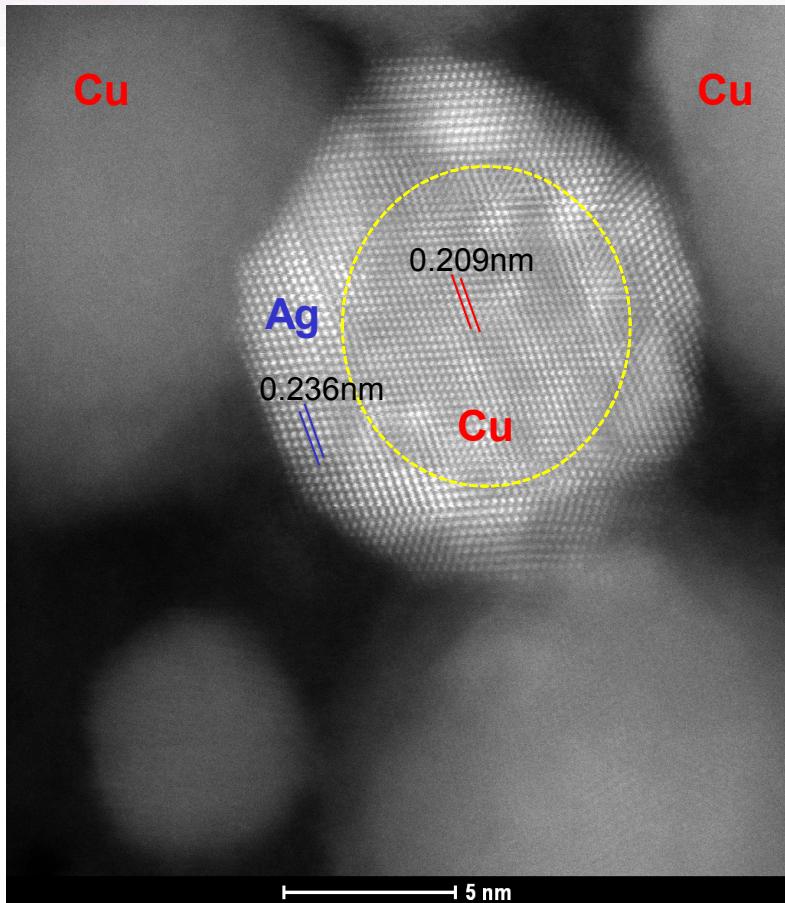
- 5nm, after 60M steps
- Shell is clearly favored at 800K

In-Situ TEM Challenges

- Electron beam induced effect
 - Electron beam exposure, even at 80 kV, during the EDS mapping leads to oxidation of Cu NPs
- Sample drift during heating and cooling

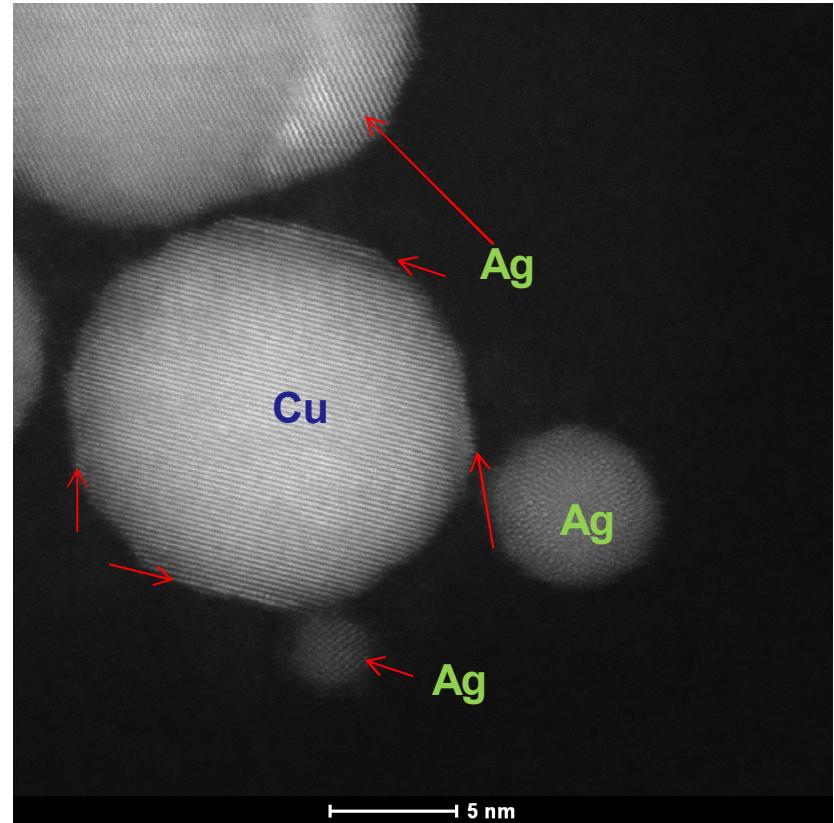
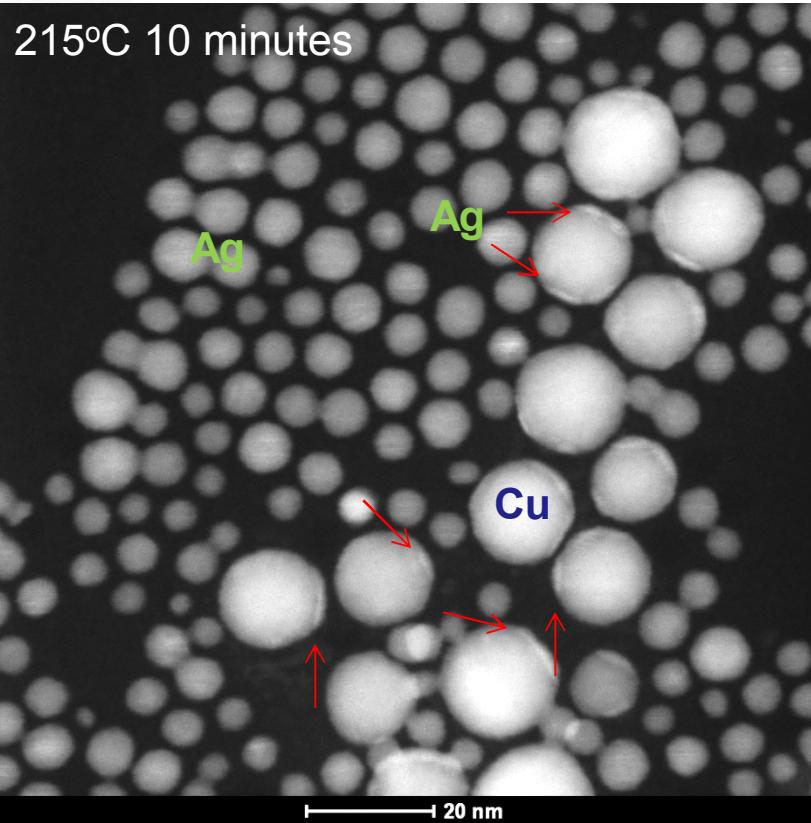


New Experimental Results



- Results from heating to 150°C
- Carefully avoid electron beam heating
- Now agrees with prediction from simulations
- ~9nm Cu core with ~2.5nm Ag-shell, preference for {111}

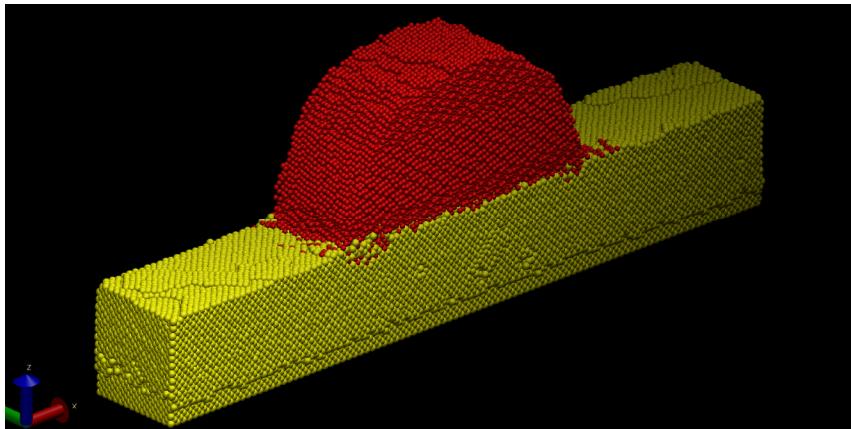
Further Demonstration of $\{111\}$



- Slightly higher temperature
- Ag shell caught in the act of formation
- Demonstrates preference for $\{111\}$ formation

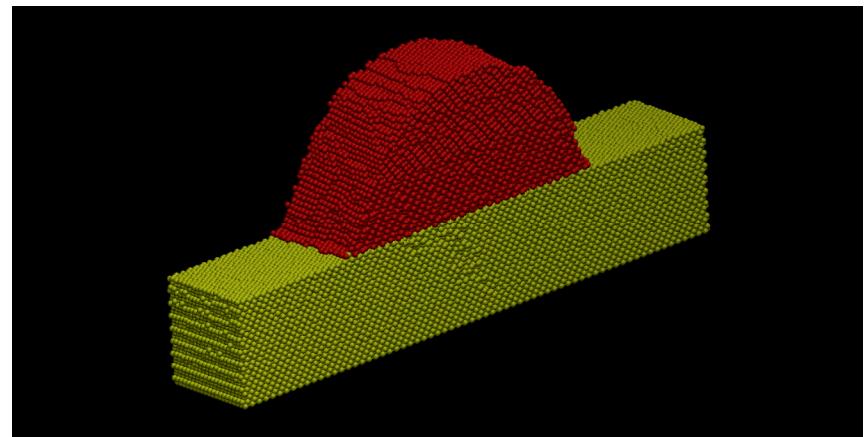


Why $\{111\}$?

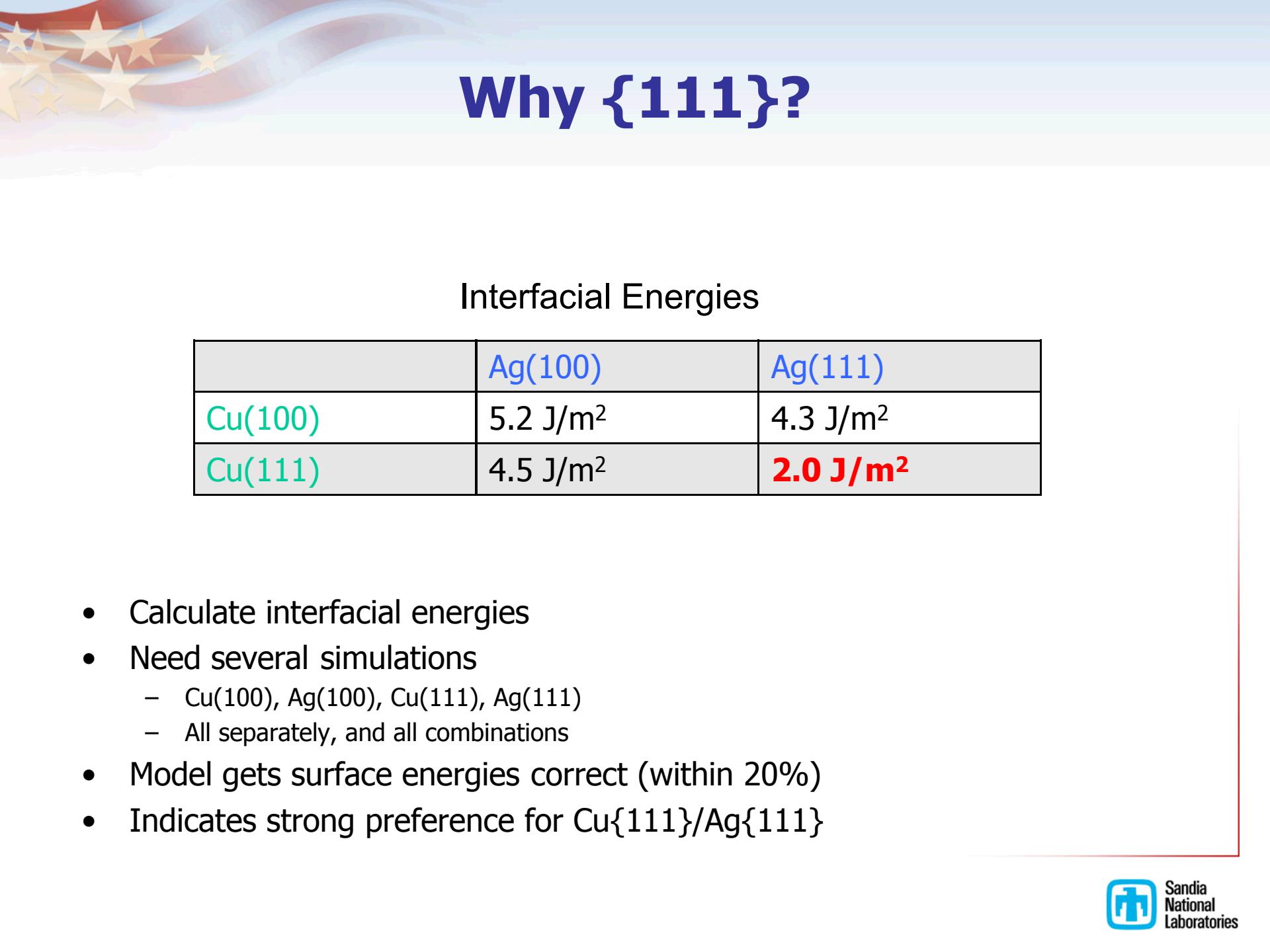


Ag on Cu{100}
~ 10 ns

Ag on Cu{111}
~ 20 ns



- Simulations of sessile drop spreading
- Run with MD at 500°C
- Infinite half-cylinder on infinite substrate
 - pseudo-2D version of drop
 - Same spreading dynamics
- Not much spreading on {100} or {111}



Why {111}?

Interfacial Energies

	Ag(100)	Ag(111)
Cu(100)	5.2 J/m ²	4.3 J/m ²
Cu(111)	4.5 J/m ²	2.0 J/m²

- Calculate interfacial energies
- Need several simulations
 - Cu(100), Ag(100), Cu(111), Ag(111)
 - All separately, and all combinations
- Model gets surface energies correct (within 20%)
- Indicates strong preference for Cu{111}/Ag{111}



Conclusions

- Nanoparticles will bond
 - Bulk phase diagram indicates differently
 - Low temperature bonding is possible
- Preference is for Ag{111} on Cu{111}
 - Predicted by models
 - Verified by experiments
- Interfacial energy is likely explanation